INTEGRATED CIRCUITS

DATA SHEET

74F259 Latch

Product specification

1989 Apr 11

IC15 Data Handbook





Latch 74F259

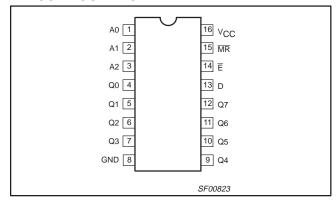
FEATURES

- Combines demultiplexer and 8-bit latch
- Serial-to-parallel capability
- Output from each storage bit available
- Random (addressable) data entry
- Easily expandable
- Common reset input
- Useful as 1-of-8 active-High decoder

DESCRIPTION

The 74F259 addressable latch has four distinct modes of operation which are selectable by controlling the Master Reset ($\overline{\text{MR}}$) and Enable ($\overline{\text{E}}$) inputs (see Function Table). In the addressable latch mode, data at the Data inputs is written into the addressed latches. The addressed latches will follow the Data input with all unaddressed latches remaining in their previous states. In the store mode, all latches remain in their previous states and are unaffected by the Data or Address inputs. To eliminate the possibility of entering erroneous data in the latches, the enable should be held High (inactive) while the address lines are changing. In the 1-of-8 decoding or demultiplexing mode ($\overline{\text{MR}}$ =E=Low), addressed outputs will follow the level of the Data input, with all other outputs Low. In the Master Reset mode, all outputs are Low and unaffected by the Address and Data inputs.

PIN CONFIGURATION



TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F259	7.5ns	31mA

ORDERING INFORMATION

	ORDER CODE	
DESCRIPTION	COMMERCIAL RANGE $V_{CC} = 5V \pm 10\%$, $T_{amb} = 0$ °C to +70°C	PKG DWG #
16-pin plastic DIP	N74F259N	SOT38-4
16-pin plastic SO	N74F259D	SOT109-1

INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

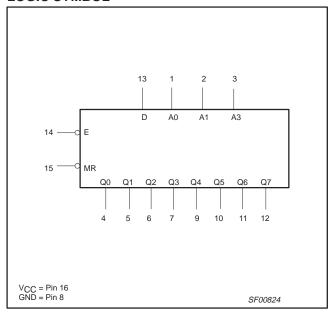
PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
D	Data input	1.0/1.0	20μA/0.6mA
A0, A1, A2	Address inputs	1.0/1.0	20μA/0.6mA
Ē	Enable input (active Low)	1.0/1.0	20μA/0.6mA
MR	Master Reset inputs (active Low)	1.0/1.0	20μA/0.6mA
Q0 – Q7	Data outputs	50/33	1.0mA/20mA

NOTE:

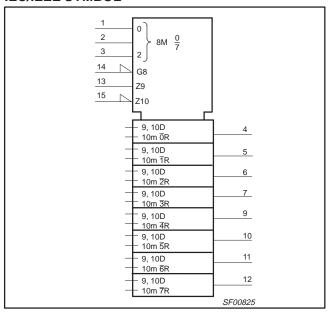
One (1.0) FAST unit load is defined as: 20µA in the High state and 0.6mA in the Low state.

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LOGIC SYMBOL



IEC/IEEE SYMBOL



FUNCTION TABLE

		INPL	JTS						OUTF	PUTS				OREDATING MODE	
MR	Ē	D	A0	A1	A2	Q0	Q1	Q2	Q3	Q4	Q5	Q6	Q7	OPERATING MODE	
L	Н	Х	Х	Х	L	L	L	L	L	L	L	L	L	Master Reset	
L	L	d	L	L	L	Q=d	L	L	L	L	L	L	L		
L	L	d	Н	L	L	L	Q=d	L	L	L	L	L	L		
L	L	d	L	Н	L	L	L	Q=d	L	L	L	L	L	Demultiplex	
	•	•	•	•	•		•	•	•	•	•	•	•	(active-High decoder	
	•	•	•	•	•		•	•	•	•			•	when D=H)	
	•	•	•	•	•			•	•	•	•		•		
L	L	d	Н	Н	Н	L	L	L	L	L	L	L	Q=d		
Н	Н	Х	Х	Х	Х	q0	q1	q2	q3	q4	q5	q6	q7	Store (do nothing)	
Н	L	d	L	L	L	Q=d	q1	q2	q3	q4	q5	q6	q7		
Н	L	d	Н	L	L	q0	Q=d	q2	q3	q4	q5	q6	q7		
Н	L	d	L	Н	L	q0	q1	Q=d	q3	q4	q5	q6	q7		
•	•	•	•	•	•		•	•	•	•	•	•	•	Addressable Latch	
•	•	•	•	•	•			•	•	•	•		•		
	•	•	•	•	•			•	•	•					
Н	L	d	Н	Н	Н	q0	q1	q2	q3	q4	q5	q6	Q=d		

H = High voltage level

L = Low voltage level

Χ

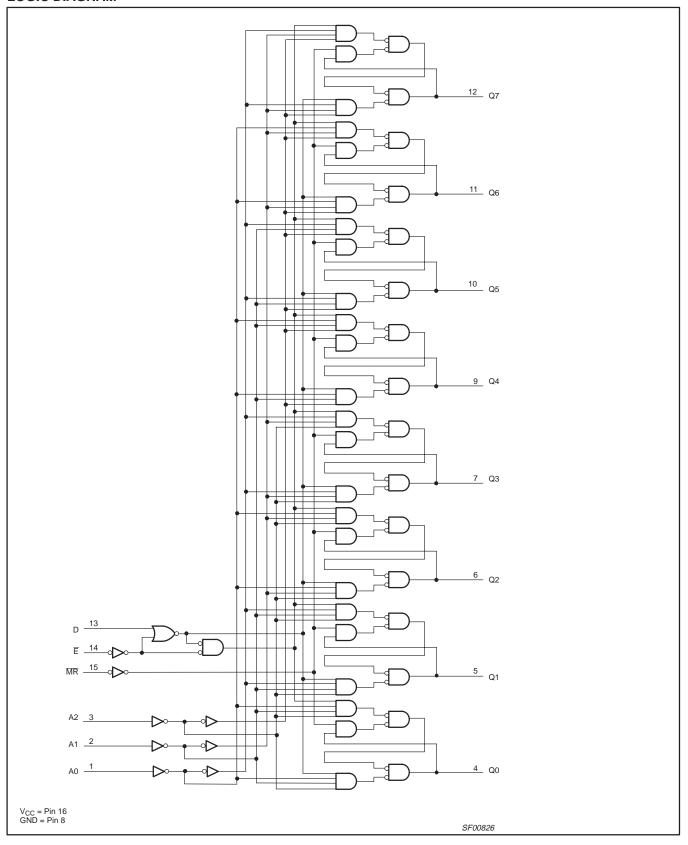
d = High or Low data one setup time prior to the Low-to-High Enable transition
q = Lower case letters indicate the state of the referenced output established during the last cycle in which it was addressed or cleared.

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LOGIC DIAGRAM



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ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limit set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V _{CC}	Supply voltage	-0.5 to +7.0	V
V _{IN}	Input voltage	-0.5 to +7.0	V
I _{IN}	Input current	-30 to +5	mA
V _{OUT}	Voltage applied to output in High output state	–0.5 to V _{CC}	V
l _{OUT}	Current applied to output in Low output state	40	mA
T _{amb}	Operating free-air temperature range	0 to +70	°C
T _{stg}	Storage temperature range	-65 to +150	°C

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER		LIMITS		UNIT
		MIN	NOM	MAX	1
V _{CC}	Supply voltage	4.5	5.0	5.5	V
V _{IH}	High-level input voltage	2.0			V
V _{IL}	Low-level input voltage			0.8	V
I _{IK}	Input clamp current			-18	mA
Іон	High-level output current			-1	mA
I _{OL}	Low-level output current			20	mA
T _{amb}	Operating free-air temperature range	0		70	°C

DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARAMETER		TEST				UNIT	
			CONDITIONS ¹	MIN	TYP ²	MAX		
V _{OH}	High-level output voltage		$V_{CC} = MIN, V_{IL} = MAX,$	2.5			V	
		$V_{IH} = MIN, I_{OL} = MAX$	±5%V _{CC}	2.7	3.4		V	
V_{OL}	Low-level output voltage	el output voltage				0.35	0.50	V
			$V_{IH} = MIN, I_{OL} = MAX$	±5%V _{CC}		0.35	0.50	V
V_{IK}	Input clamp voltage	$V_{CC} = MIN, I_I = I_{IK}$		-0.73	-1.2	V		
I _I	Input current at maximum input voltage		$V_{CC} = MAX, V_I = 7.0V$			100	μΑ	
I _{IH}	High-level input current		$V_{CC} = MAX, V_I = 2.7V$			20	μΑ	
I _{IL}	Low-level input current		$V_{CC} = MAX, V_I = 0.5V$			-0.6	mA	
I _{OS}	Short-circuit output current ³		V _{CC} = MAX	-60		-150	mA	
I _{CC}	Supply current (total)	I _{CCH}	V _{CC} = MAX			24	46	mA
		I _{CCL}		, and the second	37	75	mA	

NOTES:

- 1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
- 2. All typical values are at $V_{CC} = 5V$, $T_{amb} = 25^{\circ}C$.
- 3. To reduce the effect of external noise during test.

^{4.} Not more than one output should be shorted at a time. For testing I_{OS}, the use of High-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

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AC ELECTRICAL CHARACTERISTICS

			LIMITS							
SYMBOL	PARAMETER	TEST CONDITION	١ ١	_{mb} = +25 / _{CC} = +5\ 0pF, R _L =	/	$T_{amb} = 0^{\circ}C$ $V_{CC} = +5$ $C_L = 50pF$	UNIT			
			MIN	TYP	MAX	MIN	MAX			
t _{PLH} t _{PHL}	Propagation delay D to Qn	Waveform NO TAG	4.0 3.0	7.0 5.0	9.0 7.0	4.0 2.5	10.0 7.5	ns		
t _{PLH} t _{PHL}	Propagation delay E to Qn	Waveform NO TAG	4.5 3.0	8.0 5.0	10.5 7.0	4.5 3.0	12.0 8.0	ns		
t _{PLH} t _{PHL}	Propagation delay An to Qn	Waveform NO TAG	5.0 4.0	10.0 8.5	14.0 9.5	5.0 4.0	14.5 10.0	ns		
t _{PHL}	Propagation delay MR to Qn	Waveform	5.0	7.0	9.0	4.5	10.0	ns		

AC SETUP REQUIREMENTS

					LIN	IITS]
SYMBOL	PARAMETER	TEST CONDITION	V.	_{mb} = +25 _{CC} = +5.0 0pF, R _L =	V	$T_{amb} = 0^{\circ}C$ $V_{CC} = +5.$ $C_{L} = 50pF,$	UNIT	
			MIN	TYP	MAX	MIN	MAX	1
t _s (H) t _s (L)	Setup time, High or Low D to \overline{E}	Waveform NO TAG	3.0 6.5			3.0 7.0		ns
t _h (H) t _h (L)	Hold time, High or Low D to \overline{E}	Waveform NO TAG	0			0		ns
t _s (H) t _s (L)	Setup time, High or Low An to $\overline{\mathbb{E}}^1$	Waveform NO TAG	2.0 2.0			2.0 2.0		ns
t _h (H) t _h (L)	Hold time, High or Low An to $\overline{\mathbb{E}^2}$	Waveform NO TAG	0			0		ns
t _w (L)	E Pulse width, Low	Waveform NO TAG	7.5			8.0		ns
t _w (L)	MR Pulse width, Low	Waveform NO TAG	3.0			3.0		ns

NOTES:

^{1.} The Address to Enable setup time is the time before the High-to-Low Enable transition that the Address must be stable so that the correct latch is addressed and the other latches are not affected.

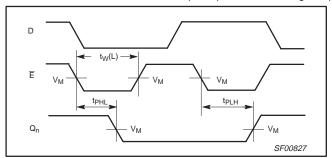
^{2.} The Address to Enable hold time is the time before the Low-to-High Enable transition that the Address must be stable so that the correct latch is addressed and the other latches are not affected.

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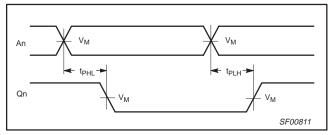
AC WAVEFORMS

For all waveforms, $V_M = 1.5V$.

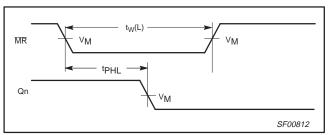
The shaded areas indicate when the input is permitted to change for predictable output performance.



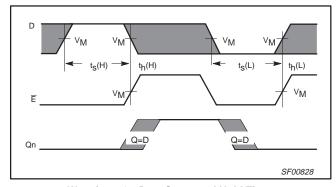
Waveform 1. Propagation Delay, Enable Input to Output, Enable Pulse Width



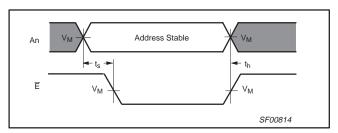
Waveform 2. Propagation Delay Address to Output



Waveform 3. Master Reset Pulse Width and Master Reset to Output Delay



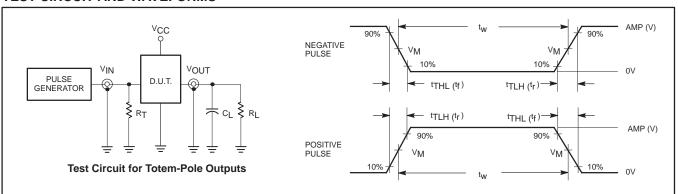
Waveform 4. Data Setup and Hold Times



Waveform 5. Address Setup and Hold Times

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TEST CIRCUIT AND WAVEFORMS



DEFINITIONS:

R_L = Load resistor; see AC ELECTRICAL CHARACTERISTICS for value.

C_L = Load capacitance includes jig and probe capacitance; see AC ELECTRICAL CHARACTERISTICS for value.

R_T = Termination resistance should be equal to Z_{OUT} of

pulse generators.

family	INP	INPUT PULSE REQUIREMENTS										
family	amplitude	V_{M}	rep. rate	t _w	t _{TLH}	t _{THL}						
74F	74F 3.0V		1MHz	500ns	2.5ns	2.5ns						

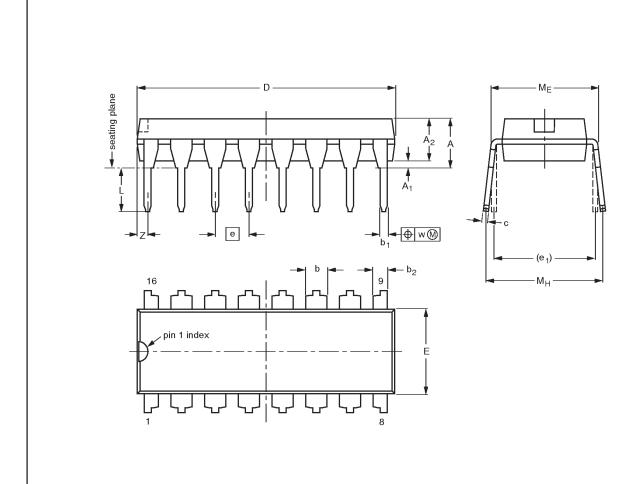
SF00006

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DIP16: plastic dual in-line package; 16 leads (300 mil)

SOT38-4



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	b ₂	С	D ⁽¹⁾	E (1)	е	e ₁	L	ME	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	1.25 0.85	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	0.76
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.049 0.033	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.030

scale

1<u>0</u> mm

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

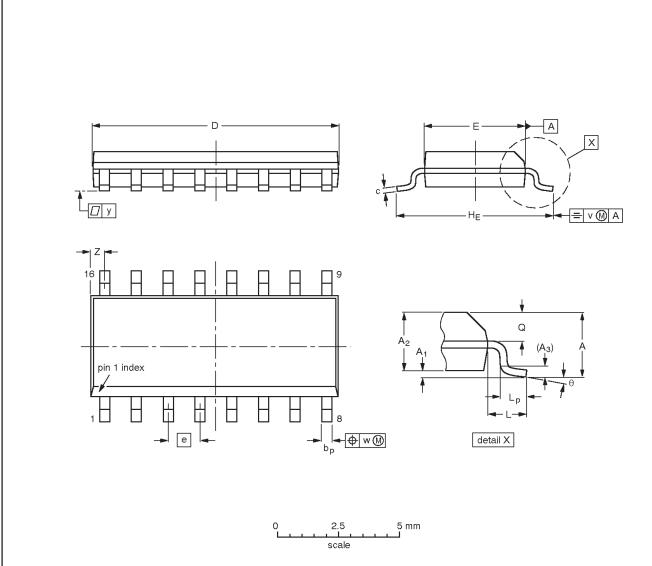
OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT38-4					92-11-17 95-01-14

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SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

							_											
UNIT	A max.	A ₁	A ₂	A ₃	bp	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Ø	v	w	у	Z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inches	0.069	0.010 0.004	0.057 0.049	0.01		0.0100 0.0075		0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016	0.028 0.020	0.01	0.01	0.004	0.028 0.012	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	1330E DATE
SOT109-1	076E07S	MS-012AC				95-01-23 97-05-22

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NOTES

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Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.
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^[1] Please consult the most recently issued datasheet before initiating or completing a design.

Definitions

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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